REMARKS

The Official Action dated June 11, 2003 has been received and its contents carefully noted. In view thereof, claim 34 has been amended in order to better define that which Applicants' regard as the invention.

Claims 23-27, 29, 32 and 34-40 are presently pending in the instant application. By the present amendment, claim 34 has been amended. Applicant acknowledges, with appreciation, the allowance of claims 23-27, 29, 32 and 35-40.

Turning to the Office Action, on page 2, claim 34 is rejected under 35 U.S.C. 102(e) as being anticipated by U.S. Patent No. 6,046,503 to Weigand et al. (hereinafter Weigand). In view of the amendment to claim 34 above and the comments below, Applicant respectfully traverses this rejection.

The Weigand patent is directed to a metallization system having an enhanced thermal conductivity (Abstract).

On the other hand, the present invention, as set forth in claim 34, is directed to a semiconductor device, comprising: a conductor layer formed on a semiconductor substrate, a dielectric film formed on the conductor layer; and a conductor line formed on the dielectric film, wherein the conductor layer is not formed in a region directly below the conductor line but in both sides of the region thereof, and the dielectric film consists of two dielectric layers with mutually different dielectric constants, and the conductor line transmits an RF signal by using the conductor layer as a ground. Applicant respectfully submits that Weigand does not teach or suggest this combination of elements.

For example, Weigand does not disclose or suggest that the conductor line transmits an RF signal by using the conductor layer as a ground. On page 2 of the Office Action, the Examiner associates Wigand's conductor 40a to the conductor line of the present invention. However, Applicant respectfully submits that Weigand fails to disclose a grounded conductor layer and further fails to disclose that the conductor 40a in Weigand transmits the radio frequencies. Instead, Weigand et al. merely discloses a metallization system including a tungsten plug 34 embedded in a through hole so as to enhance heat release of an integrated circuit, and the through hole reaches a substrate 10 by passing through multi-level patterns composed of a dielectric layer 24 and a diamond layer having a high thermal conductivity.

Weigand does not disclose whether a metal conductor 18 or the tungsten plug 34 is grounded, or how it transmits radio frequencies. Thus, Applicant respectfully requests reconsideration and withdrawal of the rejection.

Therefore, in view of the foregoing it is respectfully requested that the rejections of record be reconsidered and withdrawn by the Examiner, that claim 34 be allowed and that the application be passed to issue.

Should the Examiner believe a conference would be of benefit in expediting the prosecution of the instant application, he is hereby invited to telephone counsel to arrange such a conference.

Respectfully submitted,

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